

Atom Adhesives AA-BOND G298 Epoxy Adhesive

Category : Polymer , Thermoset , Epoxy , Epoxy Adhesive

Material Notes:

AA-BOND G298 is a two component, gold-filled, electrically and thermally conductive epoxy designed for hybrid microelectronic and semiconductor packaging. Appearance: Resin: Brown, Hardener: Dark Brown Cure Type: Heat cure or Room temperature Benefits: Gold filled epoxy allows for antioxidation of contacts and terminals in high reliability devices. It can be used in medical circuits using traditional hybrid packaging technologies. High viscosity paste allows for precision deposition onto circuits by means of printing and delicate hand processes. Mix Ratio by weight: 100:13.5/Resin:Hardener Substrates: Metals, ceramics, glass, glass fabrics, wood leather and rigid plastics Typical Application: Adhesive for joining die and SMDs onto the hybrid circuits. Repairing defective Au thick-film conductor traces and contact pads. Resisting oxidation and electromigration in high-reliability microelectronics. Joining material as alternative to high temperature Au-Sn eutectic solders processes exceeding 300°C. Information provided by Atom Adhesives

Order this product through the following link:

http://www.lookpolymers.com/polymer_Atom-Adhesives-AA-BOND-G298-Epoxy-Adhesive.php

Physical Properties	Metric	English	Comments
Particle Size	<= 50 µm	<= 50 µm	uncured
Viscosity	>= 400000 cP	>= 400000 cP	0.5 rpm, uncured

Mechanical Properties	Metric	English	Comments
Shear Strength	11.7 MPa	1700 psi	Die, @ 23°C: = 5 Kg

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	275 °C	527 °F	Continuous
	375 °C	707 °F	Intermittent
Minimum Service Temperature, Air	-55.0 °C	-67.0 °F	Intermittent
	-55.0 °C	-67.0 °F	Continuous
Glass Transition Temp, Tg	>= 100 °C	>= 212 °F	Dynamic Cure 20–200°C /ISO 25 Min; Ramp -10–200°C @ 20°C/Min
Decomposition Temperature	483 °C	901 °F	TGA, Degradation Temp, uncured

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.00090 ohm-cm	<= 0.00090 ohm-cm	

Processing Properties	Metric	English	Comments
	15.0 min	0.250 hour	

Cure Time Processing Properties	Metric @ Temperature 120 °C	English @ Temperature 248 °F	Comments
	90.0 min	1.50 hour	
	@Temperature 80.0 °C	@Temperature 176 °F	
	600 min	10.0 hour	
	@Temperature 50.0 °C	@Temperature 122 °F	
	1440 min	24.0 hour	
	@Temperature 25.0 °C	@Temperature 77.0 °F	
Pot Life	30.0 min	30.0 min	uncured
Shelf Life	12.0 Month	12.0 Month	

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China